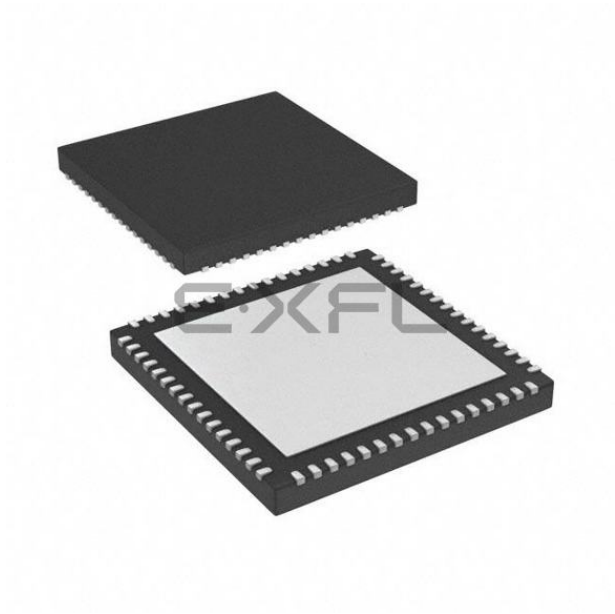
Microchip Technology - PIC32MX470F512HT-120/MR Datasheet



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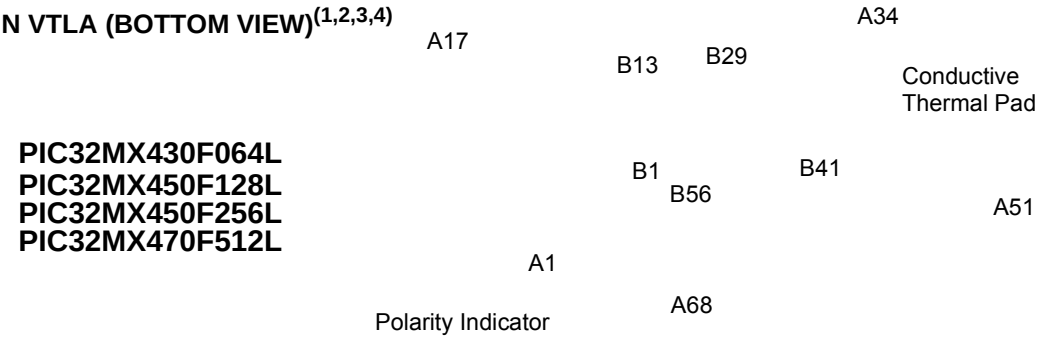
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	49
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx470f512ht-120-mr

TABLE 7: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)

124-PIN VTLA (BOTTOM VIEW)(1,2,3,4)



Package Bump #	Full Pin Name	Package Bump #	Full Pin Name
B7	$\overline{MCLR}$	B32	SDA2/RA3
B8	VSS	B33	TDO/RA5
B9	TMS/CTED1/RA0	B34	OSC1/CLKI/RC12
B10	RPE9/RE9	B35	No Connect
B11	AN4/C1INB/RB4	B36	SCL1/RPA14/RA14
B12	VSS	B37	RPD8/RTCC/RD8
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	B38	RPD10/SCK1/PMCS2/RD10
B14	PGED1/AN0/RPB0/RB0	B39	RPD0/INT0/RD0
B15	No Connect	B40	SOSCO/RPC14/T1CK/RC14
B16	PGED2/AN7/RPB7/CTED3/RB7	B41	VSS
B17	VREF+/CVREF+/PMA6/RA10	B42	AN25/RPD2/RD2
B18	AVSS	B43	RPD12/PMD12/RD12
B19	AN9/RPB9/CTED4/RB9	B44	RPD4/PMWR/RD4
B20	AN11/PMA12/RB11	B45	PMD14/RD6
B21	VDD	B46	No Connect
B22	RPF13/RF13	B47	No Connect
B23	AN12/PMA11/RB12	B48	VCAP
B24	AN14/RPB14/CTED5/PMA1/RB14	B49	RPF0/PMD11/RF0
B25	VSS	B50	RPG1/PMD9/RG1
B26	RPD14/RD14	B51	TRCLK/RA6
B27	RPF4/PMA9/RF4	B52	PMD0/RE0
B28	No Connect	B53	VDD
B29	RPF8/RF8	B54	TRD2/RG14
B30	VUSB3V3	B55	TRD0/RG13
B31	D+	B56	RPE3/CTPLS/PMD3/RE3

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: Shaded package bumps are 5V tolerant.

4: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

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1.0 DEVICE OVERVIEW

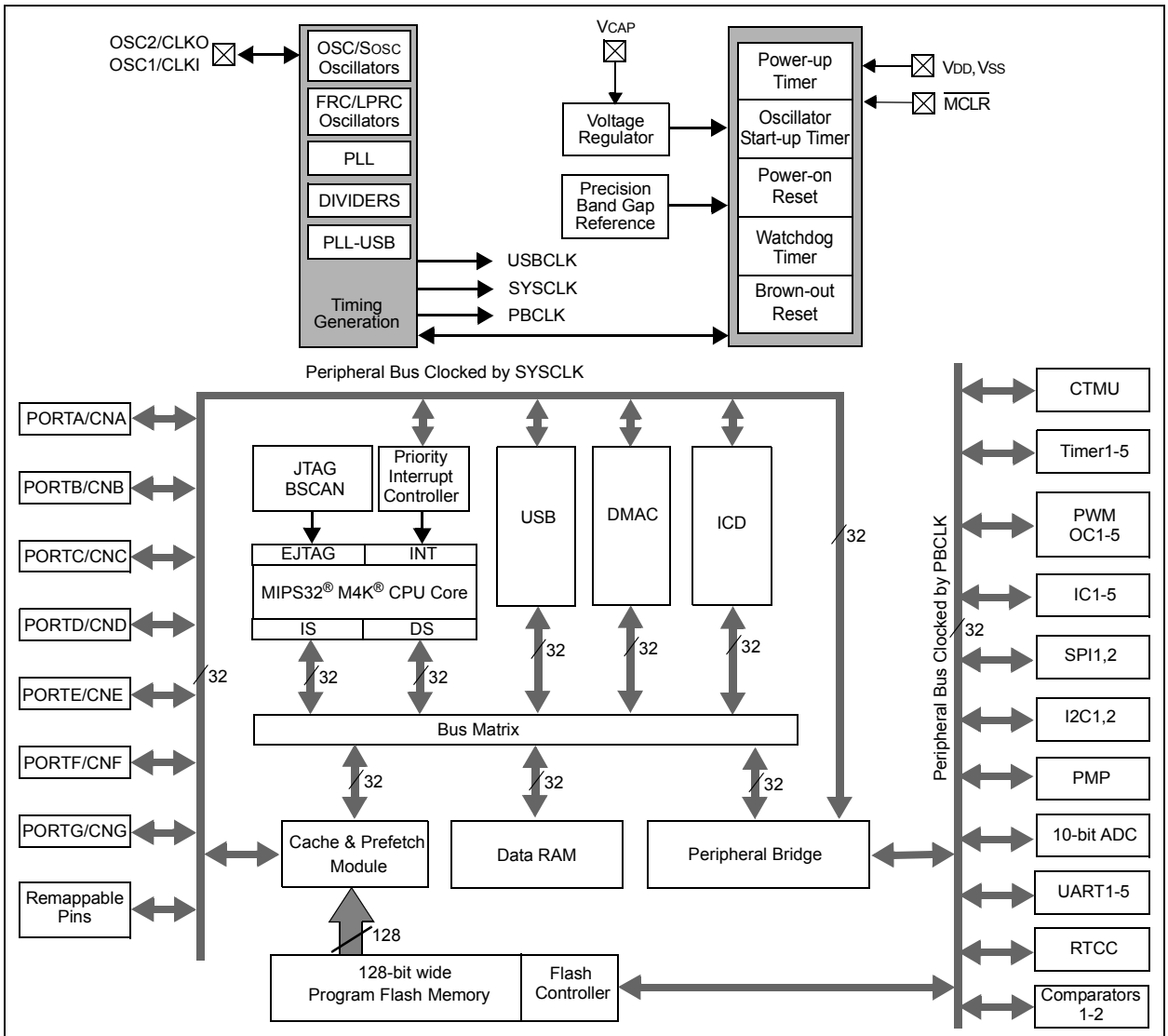
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This document contains device-specific information for PIC32MX330/350/370/430/450/470 devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX330/350/370/430/450/470 family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: PIC32MX330/350/370/430/450/470 BLOCK DIAGRAM



Note: Not all features are available on all devices. Refer to **TABLE 1: "PIC32MX330/350/370/430/450/470 Controller Family Features"** for the list of features by device.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
PMD3	63	99	B56	I/O	TTL/ST	Parallel Master Port Data (Demultiplexed Master mode) or Address/Data (Multiplexed Master modes)
PMD4	64	100	A67	I/O	TTL/ST	
PMD5	1	3	B2	I/O	TTL/ST	
PMD6	2	4	A4	I/O	TTL/ST	
PMD7	3	5	B3	I/O	TTL/ST	
PMD8	—	90	A61	I/O	TTL/ST	
PMD9	—	89	B50	I/O	TTL/ST	
PMD10	—	88	A60	I/O	TTL/ST	
PMD11	—	87	B49	I/O	TTL/ST	
PMD12	—	79	B43	I/O	TTL/ST	
PMD13	—	80	A54	I/O	TTL/ST	
PMD14	—	83	B45	I/O	TTL/ST	
PMD15	—	84	A56	I/O	TTL/ST	
PMRD	53	82	A55	O	—	Parallel Master Port Read Strobe
PMWR	52	81	B44	O	—	Parallel Master Port Write Strobe
V_{BUS}(2)	34	54	A37	I	Analog	USB Bus Power Monitor
V_{USB3V3}(2)	35	55	B30	P	—	USB internal transceiver supply. If the USB module is not used, this pin must be connected to V_{DD}.
V_{BUSON}(2)	11	20	A12	O	—	USB Host and OTG bus power control Output
D+(2)	37	57	B31	I/O	Analog	USB D+
D-(2)	36	56	A38	I/O	Analog	USB D-
USBID(2)	33	51	A35	I	ST	USB OTG ID Detect
PGED1	16	25	B14	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 1
PGEC1	15	24	A15	I	ST	Clock Input pin for Programming/Debugging Communication Channel 1
PGED2	18	27	B16	I/O	ST	Data I/O Pin for Programming/Debugging Communication Channel 2
PGEC2	17	26	A20	I	ST	Clock Input Pin for Programming/Debugging Communication Channel 2
PGED3	13	22	A13	I/O	ST	Data I/O Pin for Programming/Debugging Communication Channel 3
PGEC3	14	23	B13	I	ST	Clock Input Pin for Programming/Debugging Communication Channel 3
TRCLK	—	91	B51	O	—	Trace clock
TRD0	—	97	B55	O	—	Trace Data bit 0
TRD1	—	96	A65	O	—	Trace Data bit 1
TRD2	—	95	B54	O	—	Trace Data bit 2
TRD3	—	92	A62	O	—	Trace Data bit 3
CTED1	—	17	B9	I	ST	CTMU External Edge Input 1
CTED2	—	38	A26	I	ST	CTMU External Edge Input 2
CTED3	18	27	B16	I	ST	CTMU External Edge Input 3

Legend: CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; TTL = TTL input buffer; Analog = Analog input; O = Output; P = Power; I = Input

Note 1: This pin is only available on devices without a USB module.

2: This pin is only available on devices with a USB module.

3: This pin is not available on 64-pin devices.

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REGISTER 4-2: BMXDKPBA: DATA RAM KERNEL PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDKPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDKPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDKPBA<15:10>:** DRM Kernel Program Base Address bits
When non-zero, this value selects the relative base address for kernel program space in RAM

bit 9-0 **BMXDKPBA<9:0>:** Read-Only bits
Value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernel mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

5.1 Control Registers

TABLE 5-1: FLASH CONTROLLER REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F400	NVMCON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	WR	WREN	WRERR	LVDERR	LVDSTAT	—	—	—	—	—	—	—	NVMOP<3:0>				0000
F410	NVMKEY	31:16	NVMKEY<31:0>																0000
		15:0																	0000
F420	NVMADDR(1)	31:16	NVMADDR<31:0>																0000
		15:0																	0000
F430	NVMDATA	31:16	NVMDATA<31:0>																0000
		15:0																	0000
F440	NVMSRC ADDR	31:16	NVMSRCADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

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REGISTER 10-4: DCRCCON: DMA CRC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0
	—	—	BYTO<1:0>		WBO(1)	—	—	BITO(1)
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	PLEN<4:0>				
7:0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	CRCEN	CRCAPP(1)	CRCTYP	—	—	CRCCH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-30 **Unimplemented:** Read as '0'

bit 29-28 **BYTO<1:0>:** CRC Byte Order Selection bits
- 11 = Endian byte swap on half-word boundaries (i.e., source half-word order with reverse source byte order per half-word)
- 10 = Swap half-words on word boundaries (i.e., reverse source half-word order with source byte order per half-word)
- 01 = Endian byte swap on word boundaries (i.e., reverse source byte order)
- 00 = No swapping (i.e., source byte order)

bit 27 **WBO:** CRC Write Byte Order Selection bit(1)
- 1 = Source data is written to the destination re-ordered as defined by BYTO<1:0>
- 0 = Source data is written to the destination unaltered

bit 26-25 **Unimplemented:** Read as '0'

bit 24 **BITO:** CRC Bit Order Selection bit(1)

When CRCTYP (DCRCCON<15>) = 1 (CRC module is in IP Header mode):
- 1 = The IP header checksum is calculated Least Significant bit (LSb) first (i.e., reflected)
- 0 = The IP header checksum is calculated Most Significant bit (MSb) first (i.e., not reflected)

When CRCTYP (DCRCCON<15>) = 0 (CRC module is in LFSR mode):
- 1 = The LFSR CRC is calculated Least Significant bit first (i.e., reflected)
- 0 = The LFSR CRC is calculated Most Significant bit first (i.e., not reflected)

bit 23-13 **Unimplemented:** Read as '0'

bit 12-8 **PLEN<4:0>:** Polynomial Length bits(1)

When CRCTYP (DCRCCON<15>) = 1 (CRC module is in IP Header mode):
These bits are unused.

When CRCTYP (DCRCCON<15>) = 0 (CRC module is in LFSR mode):
Denotes the length of the polynomial – 1.

bit 7 **CRCEN:** CRC Enable bit
- 1 = CRC module is enabled and channel transfers are routed through the CRC module
- 0 = CRC module is disabled and channel transfers proceed normally

Note 1: When WBO = 1, unaligned transfers are not supported and the CRCAPP bit cannot be set.

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11.0 USB ON-THE-GO (OTG)

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 27. "USB On-The-Go (OTG)"** (DS60001126), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Universal Serial Bus (USB) module contains analog and digital components to provide a USB 2.0 full-speed and low-speed embedded host, full-speed device or OTG implementation with a minimum of external components. This module in Host mode is intended for use as an embedded host and therefore does not implement a UHCI or OHCI controller.

The USB module consists of the clock generator, the USB voltage comparators, the transceiver, the Serial Interface Engine (SIE), a dedicated USB DMA controller, pull-up and pull-down resistors, and the register interface. A block diagram of the PIC32 USB OTG module is presented in Figure 11-1.

The clock generator provides the 48 MHz clock required for USB full-speed and low-speed communication. The voltage comparators monitor the voltage on the VBUS pin to determine the state of the bus. The transceiver provides the analog translation between the USB bus and the digital logic. The SIE is a state machine that transfers data to and from the endpoint buffers and generates the hardware protocol for data transfers. The USB DMA controller transfers data between the data buffers in RAM and the SIE. The integrated pull-up and pull-down resistors eliminate the need for external signaling components. The register interface allows the CPU to configure and communicate with the module.

The PIC32 USB module includes the following features:

- USB full-speed support for host and device
- Low-speed host support
- USB OTG support
- Integrated signaling resistors
- Integrated analog comparators for VBUS monitoring
- Integrated USB transceiver
- Transaction handshaking performed by hardware
- Endpoint buffering anywhere in system RAM
- Integrated DMA to access system RAM and Flash

Note: The implementation and use of the USB specifications, and other third party specifications or technologies, may require licensing; including, but not limited to, USB Implementers Forum, Inc. (also referred to as USB-IF). The user is fully responsible for investigating and satisfying any applicable licensing obligations.

REGISTER 11-10: U1STAT: USB STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-x	R-x	R-x	R-x	R-x	R-x	U-0	U-0
	ENDPT<3:0>				DIR	PPBI	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-4 **ENDPT<3:0>:** Encoded Number of Last Endpoint Activity bits
(Represents the number of the BDT, updated by the last USB transfer.)

1111 = Endpoint 15
1110 = Endpoint 14
•
•
•
0001 = Endpoint 1
0000 = Endpoint 0

bit 3 **DIR:** Last BD Direction Indicator bit

1 = Last transaction was a transmit transfer (TX)
0 = Last transaction was a receive transfer (RX)

bit 2 **PPBI:** Ping-Pong BD Pointer Indicator bit

1 = The last transaction was to the ODD BD bank
0 = The last transaction was to the EVEN BD bank

bit 1-0 **Unimplemented:** Read as '0'

Note: The U1STAT register is a window into a 4-byte FIFO maintained by the USB module. U1STAT value is only valid when the TRNIF bit (U1IR<3>) is active. Clearing the TRNIF bit advances the FIFO. Data in register is invalid when the TRNIF bit = 0.

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REGISTER 18-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 17 **SPIFE:** Frame Sync Pulse Edge Select bit (Framed SPI mode only)
1 = Frame synchronization pulse coincides with the first bit clock
0 = Frame synchronization pulse precedes the first bit clock

bit 16 **ENHBUF:** Enhanced Buffer Enable bit(2)
1 = Enhanced Buffer mode is enabled
0 = Enhanced Buffer mode is disabled

bit 15 **ON:** SPI Peripheral On bit(1)
1 = SPI Peripheral is enabled
0 = SPI Peripheral is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
1 = Discontinue operation when CPU enters in Idle mode
0 = Continue operation in Idle mode

bit 12 **DISSDO:** Disable SDOx pin bit
1 = SDOx pin is not used by the module. Pin is controlled by associated PORT register
0 = SDOx pin is controlled by the module

bit 11-10 **MODE<32,16>:** 32/16-Bit Communication Select bits

When AUDEN = 1:

MODE32	MODE16	Communication
1	1	24-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
1	0	32-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
0	1	16-bit Data, 16-bit FIFO, 32-bit Channel/64-bit Frame
0	0	16-bit Data, 16-bit FIFO, 16-bit Channel/32-bit Frame

When AUDEN = 0:

MODE32	MODE16	Communication
1	x	32-bit
0	1	16-bit
0	0	8-bit

bit 9 **SMP:** SPI Data Input Sample Phase bit
Master mode (MSTEN = 1):
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
Slave mode (MSTEN = 0):
SMP value is ignored when SPI is used in Slave mode. The module always uses SMP = 0.

bit 8 **CKE:** SPI Clock Edge Select bit(3)
1 = Serial output data changes on transition from active clock state to Idle clock state (see CKP bit)
0 = Serial output data changes on transition from Idle clock state to active clock state (see CKP bit)

bit 7 **SSEN:** Slave Select Enable (Slave mode) bit
1 = $\overline{SSx}$ pin used for Slave mode
0 = $\overline{SSx}$ pin not used for Slave mode, pin controlled by port function.

bit 6 **CKP:** Clock Polarity Select bit(4)
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

Note 1: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

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REGISTER 21-1: PMCON: PARALLEL PORT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON(1)	—	SIDL	ADRMUX<1:0>		PMPTTL	PTWREN	PTRDEN
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
	CSF<1:0>(2)		ALP(2)	CS2P(2)	CS1P(2)	—	WRSP	RDSP

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Parallel Master Port Enable bit(1)
- 1 = PMP is enabled
- 0 = PMP is disabled, no off-chip access performed

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue module operation when device enters Idle mode
- 0 = Continue module operation in Idle mode

bit 12-11 **ADRMUX<1:0>:** Address/Data Multiplexing Selection bits
- 11 = Lower 8 bits of address are multiplexed on PMD<15:0> pins
- 10 = All 16 bits of address are multiplexed on PMD<7:0> pins
- 01 = Lower 8 bits of address are multiplexed on PMD<7:0> pins, upper bits are on PMA<15:8>
- 00 = Address and data appear on separate pins

bit 10 **PMPTTL:** PMP Module TTL Input Buffer Select bit
- 1 = PMP module uses TTL input buffers
- 0 = PMP module uses Schmitt Trigger input buffer

bit 9 **PTWREN:** Write Enable Strobe Port Enable bit
- 1 = PMWR/PMENB port is enabled
- 0 = PMWR/PMENB port is disabled

bit 8 **PTRDEN:** Read/Write Strobe Port Enable bit
- 1 = PMRD/PMWR port is enabled
- 0 = PMRD/PMWR port is disabled

bit 7-6 **CSF<1:0>:** Chip Select Function bits(2)
- 11 = Reserved
- 10 = PMCS1 and PMCS2 function as Chip Select
- 01 = PMCS1 functions as address bit 14; PMCS2 functions as Chip Select
- 00 = PMCS1 and PMCS2 function as address bits 14 and 15, respectively

bit 5 **ALP:** Address Latch Polarity bit(2)
- 1 = Active-high ($\overline{\text{PMALL}}$ and $\overline{\text{PMALH}}$)
- 0 = Active-low (PMALL and PMALH)

bit 4 **CS2P:** Chip Select 0 Polarity bit(2)
- 1 = Active-high ($\overline{\text{PMCS2}}$)
- 0 = Active-low (PMCS2)

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON control bit.

2: These bits have no effect when their corresponding pins are used as address lines.

28.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 32. "Configuration"** (DS60001124) and **Section 33. "Programming and Diagnostics"** (DS60001129), which are available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX330/350/370/430/450/470 family of devices include several features intended to maximize application flexibility and reliability and minimize cost through elimination of external components. These are:

- Flexible device configuration
- Joint Test Action Group (JTAG) interface
- In-Circuit Serial Programming™ (ICSP™)

28.1 Configuration Bits

The Configuration bits can be programmed using the following registers to select various device configurations.

- DEVCFG0: Device Configuration Word 0
- DEVCFG1: Device Configuration Word 1
- DEVCFG2: Device Configuration Word 2
- DEVCFG3: Device Configuration Word 3
- CFGCON: Configuration Control Register

In addition, the DEVID register (Register 28-6) provides device and revision information.

REGISTER 28-1: DEVCFG0: DEVICE CONFIGURATION WORD 0

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-0	r-1	r-1	R/P	r-1	r-1	r-1	R/P
	—	—	—	CP	—	—	—	BWP
23:16	r-1	r-1	r-1	r-1	R/P	R/P	R/P	R/P
	—	—	—	—	PWP<7:4>			
15:8	R/P	R/P	R/P	R/P	r-1	r-1	r-1	r-1
	PWP<3:0>				—	—	—	—
7:0	r-1	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	—	—	—	ICESEL<1:0>		JTAGEN(1)	DEBUG<1:0>	

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Reserved:** Write '0'

bit 30-29 **Reserved:** Write '1'

bit 28 **CP:** Code-Protect bit

Prevents boot and program Flash memory from being read or modified by an external programming device.
1 = Protection is disabled
0 = Protection is enabled

bit 27-25 **Reserved:** Write '1'

bit 24 **BWP:** Boot Flash Write-Protect bit

Prevents boot Flash memory from being modified during code execution.
1 = Boot Flash is writable
0 = Boot Flash is not writable

bit 23-20 **Reserved:** Write '1'

bit 19-12 **PWP<7:0>:** Program Flash Write-Protect bits

Prevents selected program Flash memory pages from being modified during code execution. The PWP bits represent the one's compliment of the number of write protected program Flash memory pages.
11111111 = Disabled
11111110 = 0xBD00_0FFF
11111101 = 0xBD00_1FFF
11111100 = 0xBD00_2FFF
11111011 = 0xBD00_3FFF
11111010 = 0xBD00_4FFF
11111001 = 0xBD00_5FFF
11111000 = 0xBD00_6FFF
11110111 = 0xBD00_7FFF
11110110 = 0xBD00_8FFF
11110101 = 0xBD00_9FFF
11110100 = 0xBD00_AFFF
11110011 = 0xBD00_BFFF
11110010 = 0xBD00_CFFF
11110001 = 0xBD00_DFFF
11110000 = 0xBD00_EFFF
11101111 = 0xBD00_FFFF
.
.
.
01111111 = 0xBD07_FFFF

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

REGISTER 28-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 11-5 **Reserved:** Write '1'

bit 4-3 **ICESEL<1:0>:** In-Circuit Emulator/Debugger Communication Channel Select bits
11 = PGEC1/PGED1 pair is used
10 = PGEC2/PGED2 pair is used
01 = PGEC3/PGED3 pair is used
00 = Reserved

bit 2 **JTAGEN:** JTAG Enable bit(1)
1 = JTAG is enabled
0 = JTAG is disabled

bit 1-0 **DEBUG<1:0>:** Background Debugger Enable bits (forced to '11' if code-protect is enabled)
1x = Debugger is disabled
0x = Debugger is enabled

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

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REGISTER 28-5: CFGCON: CONFIGURATION CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
	—	—	IOLOCK(1)	PMDLOCK(1)	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0	R/W-1
	—	—	—	—	JTAGEN	TROEN	—	TDOEN

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-14 **Unimplemented:** Read as '0'

bit 13 **IOLOCK:** Peripheral Pin Select Lock bit(1)
- 1 = Peripheral Pin Select is locked. Writes to PPS registers is not allowed
- 0 = Peripheral Pin Select is not locked. Writes to PPS registers is allowed

bit 12 **PMDLOCK:** Peripheral Module Disable bit(1)
- 1 = Peripheral module is locked. Writes to PMD registers is not allowed
- 0 = Peripheral module is not locked. Writes to PMD registers is allowed

bit 11-4 **Unimplemented:** Read as '0'

bit 3 **JTAGEN:** JTAG Port Enable bit
- 1 = Enable the JTAG port
- 0 = Disable the JTAG port

bit 2 **TROEN:** Trace Output Enable bit
- 1 = Enable trace outputs and start trace clock (trace probe must be present)
- 0 = Disable trace outputs and stop trace clock

bit 1 **Unimplemented:** Read as '0'

bit 0 **TDOEN:** TDO Enable for 2-Wire JTAG
- 1 = 2-wire JTAG protocol uses TDO
- 0 = 2-wire JTAG protocol does not use TDO

Note 1: To change this bit, the unlock sequence must be performed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

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NOTES:

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TABLE 31-15: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
D312	TSET	Internal 4-bit DAC Comparator Reference Settling time.	—	—	10	µs	See **Note 1**
D313	DACREFH	CVREF Input Voltage Reference Range	AVSS	—	AVDD	V	CVRSRC with CVRSS = 0
			VREF-	—	VREF+	V	CVRSRC with CVRSS = 1
D314	DVREF	CVREF Programmable Output Range	0	—	0.625 x DACREFH	V	0 to 0.625 DACREFH with DACREFH/24 step size
			0.25 x DACREFH	—	0.719 x DACREFH	V	0.25 x DACREFH to 0.719 DACREFH with DACREFH/32 step size
D315	DACRES	Resolution	—	—	DACREFH/24		CVRCON<CVRR> = 1
			—	—	DACREFH/32		CVRCON<CVRR> = 0
D316	DACACC	Absolute Accuracy(2)	—	—	1/4	LSB	DACREFH/24, CVRCON<CVRR> = 1
			—	—	1/2	LSB	DACREFH/32, CVRCON<CVRR> = 0

Note 1: Settling time was measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but is not tested in manufacturing.

2: These parameters are characterized but not tested.

TABLE 31-16: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D321	CEFC	External Filter Capacitor Value	8	10	—	µF	Capacitor must be low series resistance (3 ohm). Typical voltage on the VCAP pin is 1.8V.

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TABLE 31-18: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
OS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 50	MHz MHz	EC **(Note 4)** ECPLL **(Note 3)**
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT **(Note 4)**
OS12			4	—	10	MHz	XTPLL **(Notes 3,4)**
OS13			10	—	25	MHz	HS **(Note 4)**
OS14			10	—	25	MHz	HSPLL **(Notes 3,4)**
OS15			32	32.768	100	kHz	SOSC **(Note 4)**
OS20	TOSC	TOSC = 1/FOSC = TCY **(Note 2)**	—	—	—	—	See parameter OS10 for FOSC value
OS30	TOSL, TOSH	External Clock In (OSC1) High or Low Time	0.45 x TOSC	—	—	ns	EC **(Note 4)**
OS31	TOSR, TOSF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x TOSC	ns	EC **(Note 4)**
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and SOSC Clock Oscillator modes)	—	1024	—	TOSC	**(Note 4)**
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	**(Note 4)**
OS42	GM	External Oscillator Transconductance (Primary Oscillator only)	—	12	—	mA/V	VDD = 3.3V, TA = +25°C **(Note 4)**

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

2: Instruction cycle period (TCY) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.

3: PLL input requirements: 4 MHz ≤ FPLLIN ≤ 5 MHz (use PLL prescaler to reduce FOSC). This parameter is characterized, but tested at 10 MHz only at manufacturing.

4: This parameter is characterized, but not tested in manufacturing.

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TABLE 31-32: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 4)**	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	Tsck + 20	—	—	ns	—
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 31-35: ADC MODULE SPECIFICATIONS (CONTINUED)

AC CHARACTERISTICS(5)			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
ADC Accuracy – Measurements with Internal VREF+/VREF-							
AD20d	Nr	Resolution	10 data bits			bits	**(Note 3)**
AD21d	INL	Integral Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD22d	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Notes 2,3)**
AD23d	GERR	Gain Error	> -4	—	< 4	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD24d	EOFF	Offset Error	> -2	—	< 2	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD25d	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance							
AD31b	SINAD	Signal to Noise and Distortion	55	58	—	dB	**(Notes 3,4)**
AD34b	ENOB	Effective Number of Bits	9	9.5	—	bits	**(Notes 3,4)**

Note 1: These parameters are not characterized or tested in manufacturing.

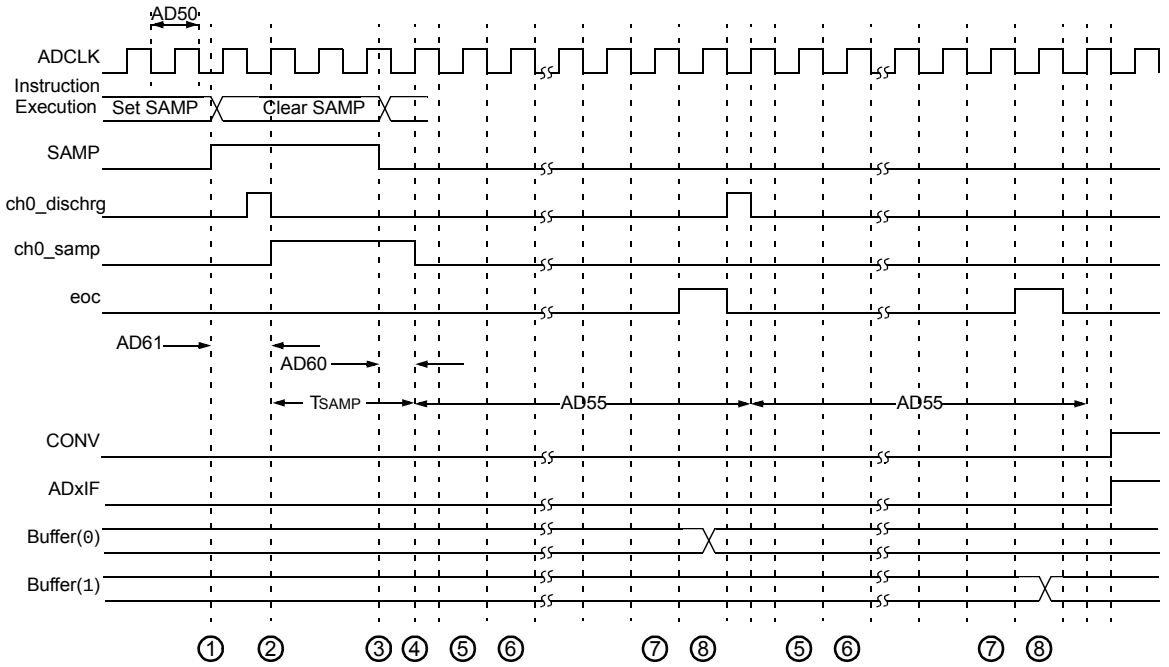
2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with a 1 kHz sine wave.

5: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 31-10 for VBORMIN values.

FIGURE 31-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets ADxCON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104) in the *"PIC32 Family Reference Manual"*.

(3) – Software clears ADxCON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

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